Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g. This device is ideal for high-frequency switching and synchronous rectification.

Application

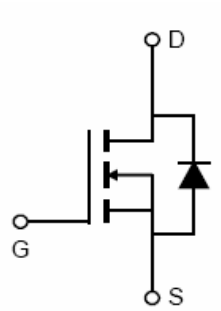
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =100V,I_D =240A
  $R_{DS(ON)}$=2.0mΩ , typical (TO-220)@ V_{GS}=10V
  $R_{DS(ON)}$=1.8mΩ , typical (TO-263)@ V_{GS}=10V
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

TO-220C

TO-263



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST10N020-TC	VST10N020	TO-220C	-	-	-
VST10N020-T3	VST10N020	TO-263	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	240	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	170	A
Pulsed Drain Current (Note 1)	I_{DM}	960	A
Maximum Power Dissipation	P_D	340	W
Derating factor		2.27	W/℃
Single pulse avalanche energy (Note 4)	E_{AS}	2784	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 175	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	0.44	℃/W
Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	60	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Parameter	Symbol	Condition		Min	Typ	Max	Unit
Off Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA		100		-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=100V,V_{GS}=0V		-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V		-	-	±100	nA
On Characteristics (Note 2)							
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA		2.0	3.0	4.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=120A	TO-220	-	2.0	2.3	mΩ
			TO-263		1.8	2.1	mΩ
Gate resistance	R_G			-	2.5	-	Ω
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=120A			200	-	S
Dynamic Characteristics (Note3)							
Input Capacitance	C_{lss}	V_{DS}=50V,V_{GS}=0V, F=1.0MHz		-	17000	-	PF
Output Capacitance	C_{oss}			-	1500	-	PF
Reverse Transfer Capacitance	C_{rss}			-	77	-	PF
Switching Characteristics (Note 3)							
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=50V,I_D=120A V_{GS}=10V,R_G=1.6Ω		-	37	-	nS
Turn-on Rise Time	t_r			-	29	-	nS
Turn-Off Delay Time	$t_{d(off)}$			-	82	-	nS
Turn-Off Fall Time	t_f			-	34	-	nS
Total Gate Charge	Q_g	V_{DS}=50V,I_D=120A, V_{GS}=10V		-	252	-	nC
Gate-Source Charge	Q_{gs}			-	72		nC
Gate-Drain Charge	Q_{gd}			-	63		nC
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=120A		-		1.2	V
Diode Forward Current (Note 2)	I_S			-	-	240	A
Reverse Recovery Time	t_{rr}	T_J = 25°C, I_F = 120A di/dt = 100A/μs (Note2)		-	105	-	nS
Reverse Recovery Charge	Qrr			-	290	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150° C. The value in any given application depends on .the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
3. Guaranteed by design, not subject to production
4. EAS condition : Tj=25℃,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25Ω

Typical Electrical and Thermal Characteristics

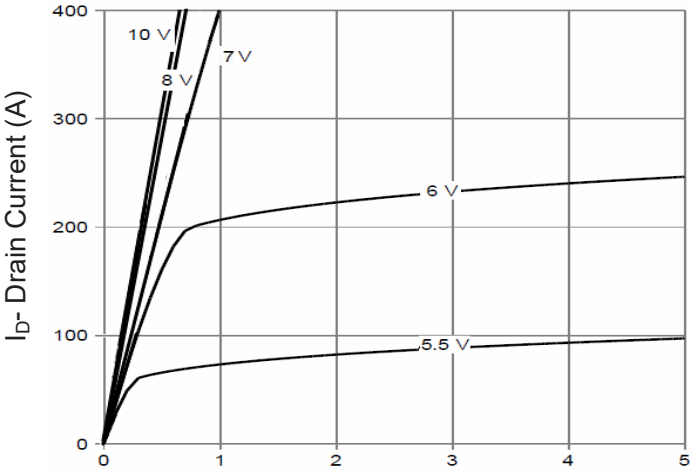


Figure 1 Output Characteristics

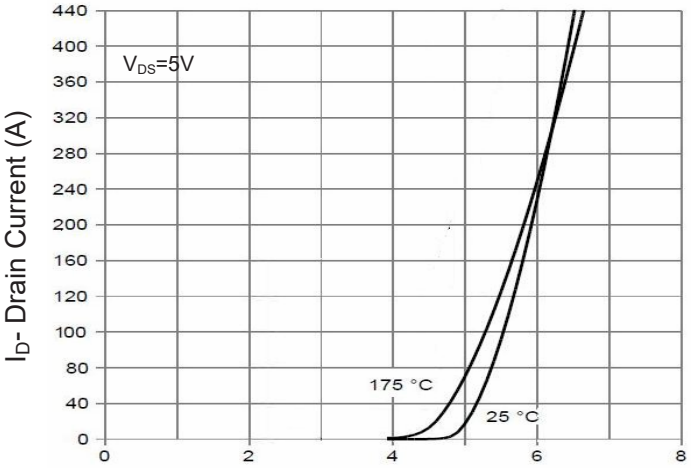


Figure 2 Transfer Characteristics

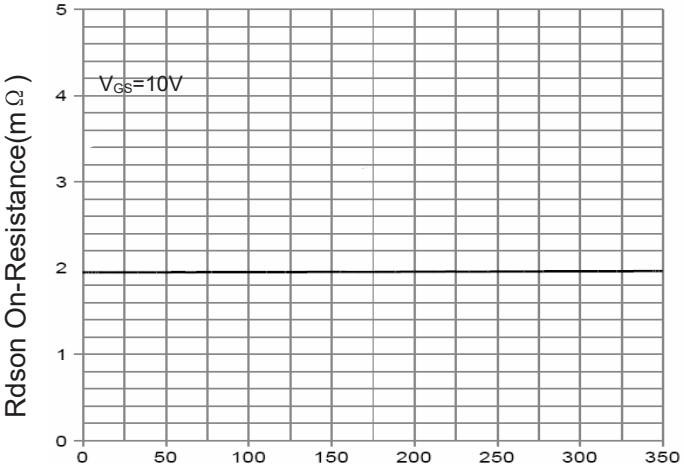


Figure 3 Rdson- Drain Current

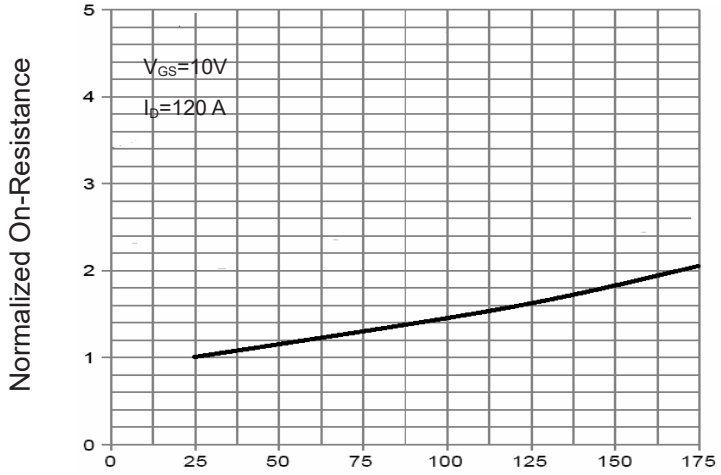


Figure 4 Rdson-Junction Temperature

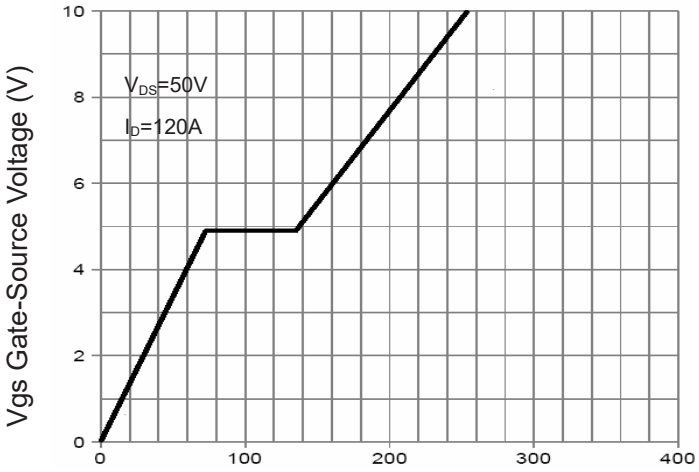


Figure 5 Gate Charge

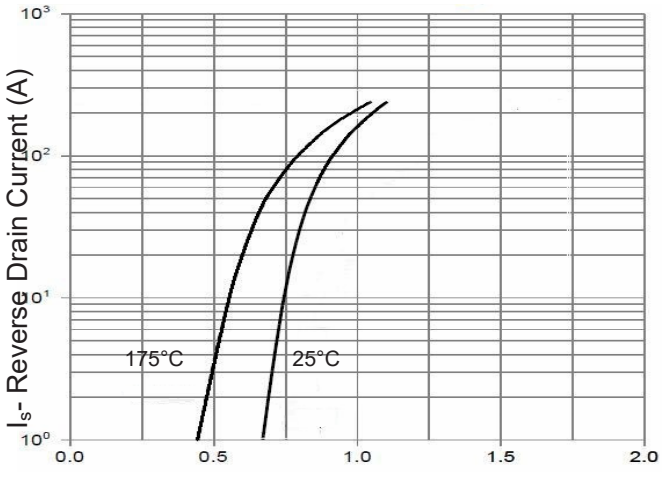


Figure 6 Source- Drain Diode Forward

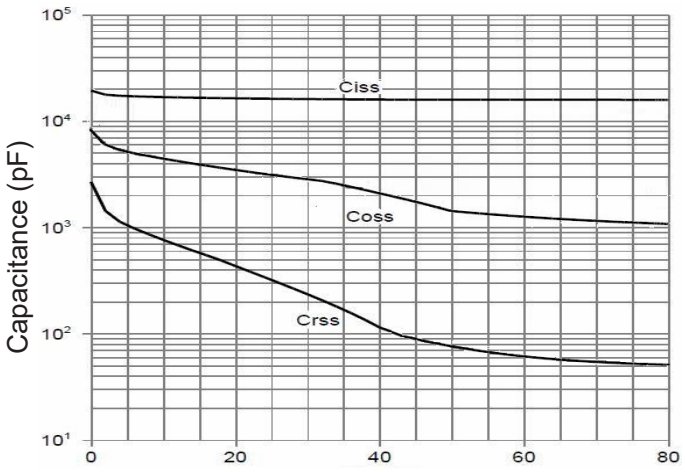


Figure 7 Capacitance vs Vds

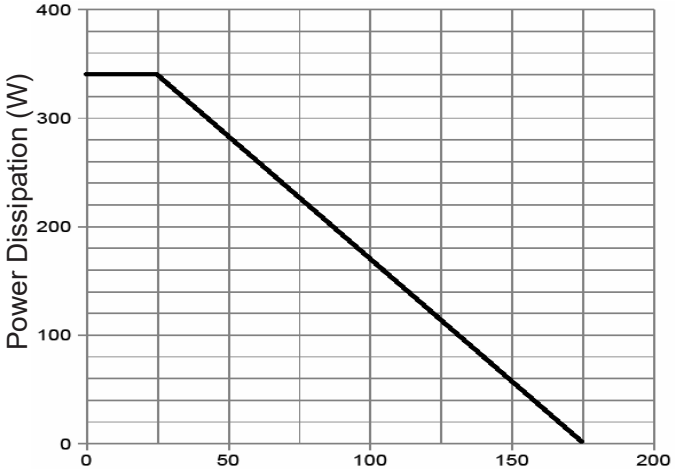


Figure 9 Power De-rating

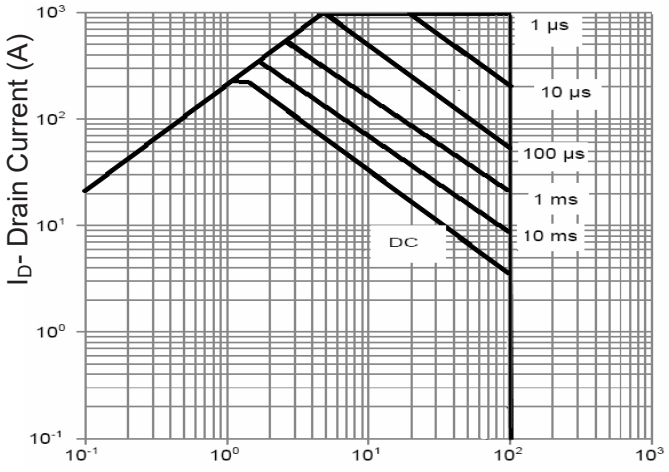


Figure 8 Safe Operation Area

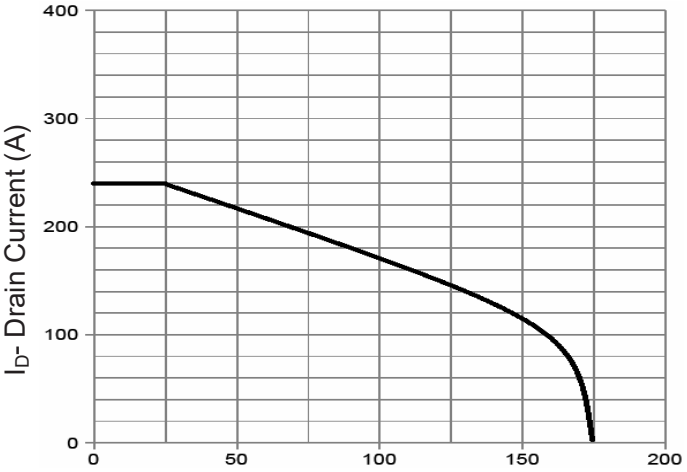


Figure 10 Current De-rating

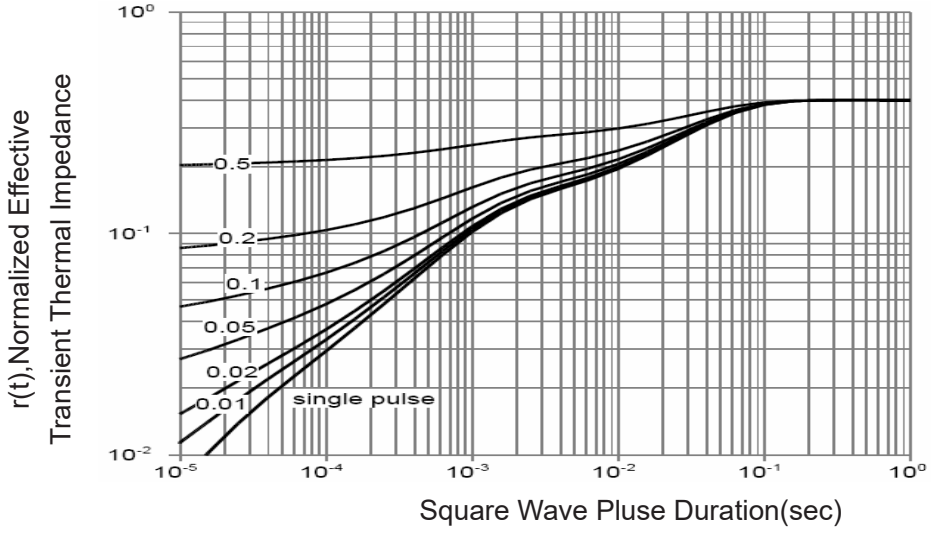
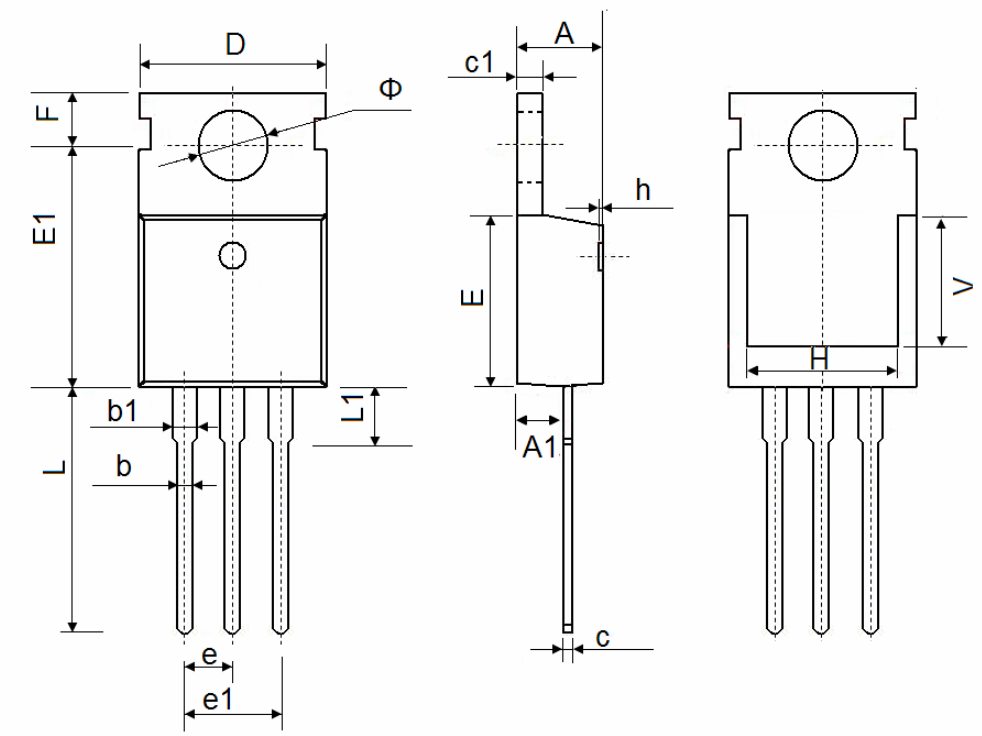


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150